

ITEM	DESC.	Q'TY	MATERIALS	TREATMENT	REMARK
1.	LEVER	1	THERMOPLASTIC PBT UL 94V-0	WHITE	
2.	SLIDER	1	THERMOPLASTIC PBT UL 94V-0	WHITH	
3.	COVER	1	THERMOPLASTIC PBT UL 94V-0	RED/BLUE/BLACK	
4.	CONTACT	1	COPPER ALLOY	GOLD PLATED	
5.	TERMINAL	1	BRASS	GOLD PLATED	
6	BASE	1	THERMOPLASTIC PA66 UL 94V-0	BLACK	
PROD. NO.: NDP - V Actuator Type:					



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1.Style:

This specification describes "DUAL IN-LINE PACKAGE SWITCHES" mainly used as signal switch of electric devices with the general requirements of mechanical and electrical characteristics.

1.1 Operating Temperature Range : -20°C ~ +70°C

1.2 Storage Temperature Range : -40°C ~ +85°C

1.3 The shelf life of product is within 6 months.

2. Current Range:

2.1 Non-Switching: 100mA, 50V DC 2.2 Switching: 25mA, 24V DC

3. Type of Actuation: Actuated by sliding

4. Test Sequence:

	ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
ELECTRIC PERFORMANCE	1	Visual Examination	By visual examination check without any out pressure & testing.	There shall be no defects that affect the serviceability of the product.
	2	Contact Resistance	1.To be measured between the two terminals associated with each switch pole.2.Measurements shall be made with a 1kHz shall current contact resistance meter.	50mΩ Max. (initial)
	3	Insulation Resistance	500V DC, 1 minute ± 5 sec.	100MΩ Min.
	4	Dielectric withstand- ing Voltage	500V AC (50Hz or 60 Hz) shall be applied between all the adjacent terminals and between the terminal and the frame for 1 minute.	There shall be no breakdown or flashover
	5	Capacitance	1 MHz ± 10 kHz	5 pF Max.
MECHANICAL PERFORMANCE	6	Operation Force	Applied in the direction of operation. ON→OFF OFF→ON	400gf Max (3.92N Max)



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	7	Stop Strength	A static load of 1 kgf(sthe operating direction direction operated for seconds.	There shall be no sign of damage mechanically	
	8	Soldering Heat Resistance	Soldering Temperatur		
			TEMP	TIME	As shown in item 2~6
l			260 °ℂ ±5 °ℂ	5±1 sec.	
MECHANICAL PERFORMANCE			(PCB is 1.6mm in thic		
	9	Vibration	Shall be vibrated in a Method 201A of MIL-3 ①Frequency: 10-55-1 ②Direction: 3 vertical the direction of open 3 Test Time: 2 hours	As shown in item 2~6	
	10	Shock	Shall be shocked in a Method 213B condition MIL-STD-202F ①Acceleration: 50G. ②Action Time: 11 ± 1 IIIIIIIIIIIIIIIIIIIIIIIIIIIIIII	As shown in item 2~6	
	11	Solderability	1.NDP(L)-V□□Soldering Temperature:245±3°C Lead-Free solder: M705E JIS Z 3282 Class A (Tin 96.5%, Silver 3%, Copper 0.5%) 2.Flux: 5-10 seconds. 3.Duration of solder Immersion: 5±1 sec.		No anti-soldering and the coverage of dipping into solder must more than 75% was requested.
DURABILITY	12	Operation Life	Measurements shall be made following the test set forth below: 1. 25 mA, 24V DC resistive load 2. Rate of Operation: 15~20 cycles/ minute 3. Cycle of Operation: 2000 cycles. 1.As shown in item 3,4 2.Contact Resistance: 100mΩ Max. (final-after test)		



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WEATHER-PROOF	13	Resistance Low Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made : ①Temperature: -40°C±3°C ②Time: 96 hours	As shown in item 2~6
	14	Resistance High Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made : ①Temperature: 85°C±2°C ②Time: 96 hours	1.As shown in item 3~6 2.Contact Resistance: 100mΩ Max.
	15	Humidity Resistance	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: ①Temperature: 40°C±2°C ②Relative Humidity:90~95% ③Time: 96 hours	1 As shown in item 4,6 2 Contact Resistance: 100mΩ Max. 3 Insulation Resistance : 10MΩ Min.

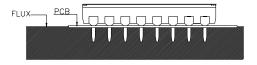
5. SOLDERING CONDITIONS:

■ Manual Soldering

Soldering Temperature	Max.350°C	
Continuous Soldering Time	Max. 5 seconds	

■ Precautions in Handling

- 1. Care should be exercised so that flux from the upper part of the printed circuit board does not adhere to the switch.
- 2. Don't clean the switch body except with top tape sealed type, which can only spray of cleaning method from top of s/w.
- 3. Please make sure that there is no flux rose over the surface of the PCB





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■ Notes on storage conditions:

Do not store in the following environment or it may affect product's function and solderbility:

- 1. temperature of -10 (max) \sim +40 (min) $^{\circ}$ C & humidity at 85% (min)
- 2. environment with corrosive gas
- 3. storage over 6 months
- 4. place of direct sunlight

Store with proper packaging conditions and to avoid loading heavy force

We suggest to use the products within 3 months or at least 6 months.

After opening the package, the rest products must be stored in the appropriate moisture-proof & airtight environment